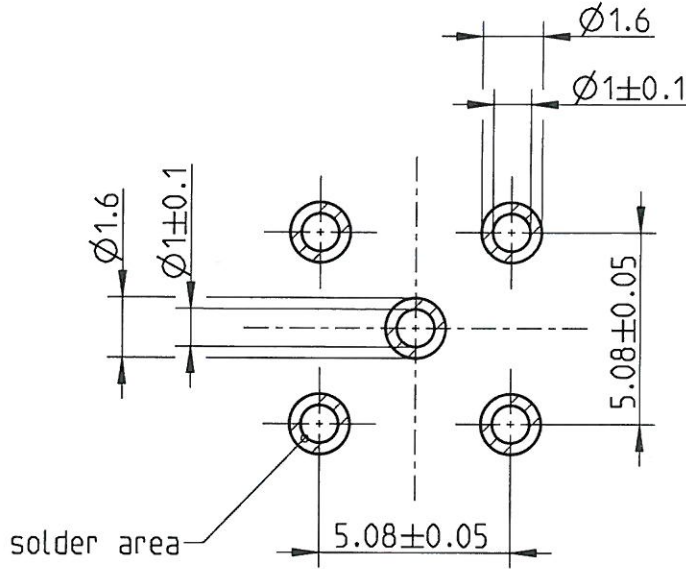


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Leiterplatten-Layout  
PCB layout  
B 30c



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formidat: TCC-FB\_05\_PR\_A4\_Einheitl  
Datei: A4\_EINHEITL\_0508.PRM  
Version: 1.0

-METRIC-



ISO-Projektion  
Methode E

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance <b>ISO 2768 RN 006-01</b> m-H dimensions <0,5 and symmetry		scale: 5:1	weight(g): surface(mm <sup>2</sup> ):
				material:	
		date name drawn 22.11.2004 A_Nobis check. 9.1.06 <i>WZ</i> appr. 09.01.06 <i>Wrautbach</i>		title: <b>Leiterplatten-Layout PCB layout</b>	
		dimensioning incl. finish		part-no.: <b>MB_30C</b>	
c00	06-0011	A_Nobis	09.01.2006	sheet: 1	
b00	05-0593	A_Nobis	04.11.2005	of: 1	
a00	04-0709	A_Nobis	22.11.2004	distribution to: FE AZ QSM RMT . X . . . .	
rev. change-no name date		distribution to:		remarks: .	